

Global Chip On Board (COB) Packaging Technology Supply, Demand and Key Producers, 2023-2029

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Abstracts

The global Chip On Board (COB) Packaging Technology market size is expected to reach \$ million by 2029, rising at a market growth of % CAGR during the forecast period (2023-2029).

Chip On Board (COB) packaging technology is a packaging technique used in electronic devices, primarily for integrated circuits (ICs). In COB packaging, the bare semiconductor chip is directly mounted and electrically connected onto a printed circuit board (PCB) or a substrate.

COB technology eliminates the need for a traditional IC package, such as a plastic or ceramic package, by directly bonding the chip to the PCB. The chip is typically wire bonded to the PCB, and then covered with a protective resin or epoxy coating.

This report studies the global Chip On Board (COB) Packaging Technology demand, key companies, and key regions.

This report is a detailed and comprehensive analysis of the world market for Chip On Board (COB) Packaging Technology, and provides market size (US\$ million) and Year-over-Year (YoY) growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Chip On Board (COB) Packaging Technology that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Chip On Board (COB) Packaging Technology total market, 2018-2029, (USD

Million)

Global Chip On Board (COB) Packaging Technology total market by region & country, CAGR, 2018-2029, (USD Million)

U.S. VS China: Chip On Board (COB) Packaging Technology total market, key domestic companies and share, (USD Million)

Global Chip On Board (COB) Packaging Technology revenue by player and market share 2018-2023, (USD Million)

Global Chip On Board (COB) Packaging Technology total market by Type, CAGR, 2018-2029, (USD Million)

Global Chip On Board (COB) Packaging Technology total market by Application, CAGR, 2018-2029, (USD Million).

This reports profiles major players in the global Chip On Board (COB) Packaging Technology market based on the following parameters – company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Cree, Inc., Lumileds, Samsung Electronics Co., Ltd., LG Innotek, OSRAM Opto Semiconductors, Bridgelux, Inc., Everlight Electronics Co., Ltd., Nichia Corporation and Epistar Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Chip On Board (COB) Packaging Technology market.

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), by player, by regions, by Type, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global Chip On Board (COB) Packaging Technology Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Chip On Board (COB) Packaging Technology Market, Segmentation by Type

Traditional COB Packaging Technology

Modular COB Packaging Technology

Others

Global Chip On Board (COB) Packaging Technology Market, Segmentation by Application

Lighting

Electronics

Industrial

Displays

Automotive

Medical and Healthcare

Others

Companies Profiled:

Cree, Inc.

Lumileds

Samsung Electronics Co., Ltd.

LG Innotek

OSRAM Opto Semiconductors

Bridgelux, Inc.

Everlight Electronics Co., Ltd.

Nichia Corporation

Epistar Corporation

Seoul Semiconductor Co., Ltd.

Sharp Corporation

Kingbright Electronic Co., Ltd.

Key Questions Answered

1. How big is the global Chip On Board (COB) Packaging Technology market?
2. What is the demand of the global Chip On Board (COB) Packaging Technology market?

3. What is the year over year growth of the global Chip On Board (COB) Packaging Technology market?
4. What is the total value of the global Chip On Board (COB) Packaging Technology market?
5. Who are the major players in the global Chip On Board (COB) Packaging Technology market?

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